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**Dunlap et al.**

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(54) **FINGERPRINT SENSOR AND BUTTON COMBINATIONS AND METHODS OF MAKING SAME**

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(58) **Field of Classification Search**  
CPC . G06K 9/0002; G06K 9/00053; G01N 27/221  
See application file for complete search history.

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(57) **ABSTRACT**

It will be understood by those skilled in the art that there is disclosed in the present application a biometric sensor that may comprise a plurality of a first type of signal traces formed on a first surface of a first layer of a multi-layer laminate package; at least one trace of a second type, formed on a second surface of the first layer or on a first surface of a second layer of the multi-layer laminate package; and connection vias in at least the first layer electrically connecting the signal traces of the first type or the signal traces of the second type to respective circuitry of the respective first or second type contained in an integrated circuit physically and electrically connected to one of the first layer, the second layer or a third layer of the multi-layer laminate package.

**19 Claims, 14 Drawing Sheets**

